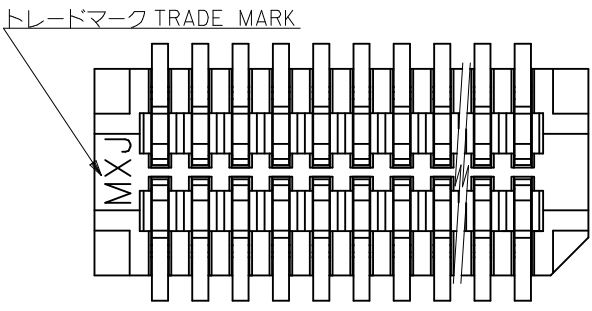


- 注記 NOTES**
1. 嵌合相手: 52465, 52588 シリーズ  
MATES WITH : 52465, 52588 SERIES
  2. ウエハーの  $\phi$  から隣接するピンの  $\phi$  迄の位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PINS.
  3. ELV 及び RoHS 適合品。  
ELV AND ROHS COMPLIANT.
  4. テール平坦度: 0.1MAX.  
COPLANARITY : 0.1MAXIMUM

0.4	17.8	16.9	15.2	---	53353-4071	40
0.4	16.2	15.3	13.6	---	53353-3671	36
0.8	13.8	12.9	11.2	53353-3029	53353-3071	30
0.4	13.0	12.1	10.4	---	53353-2871	28
0.8	10.6	9.7	8.0	---	53353-2271	22
0.4	9.8	8.9	7.2	---	53353-2071	20
0.8	9.0	8.1	6.4	---	53353-1871	18
0.4	8.2	7.3	5.6	---	53353-1671	16
0.8	7.4	6.5	4.8	---	53353-1471	14
0.4	6.6	5.7	4.0	---	53353-1271	12
0.8	5.8	4.9	3.2	---	53353-1071	10
D	C	B	(A)	TRAY PACKAGE	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.		CIRCUIT
				CONNECTOR SERIES No. : 53353-**29		

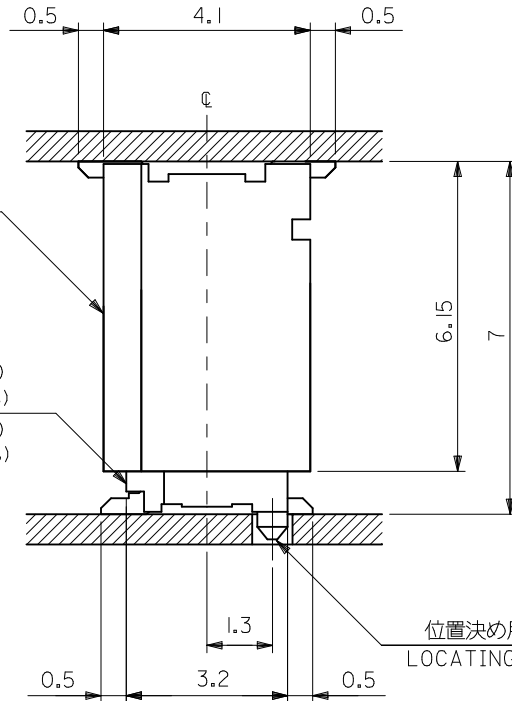


<b>REVISED</b> EC NO: J2011-0630 DRWN:KTOYODA 2010/11/01 CHKD:MSASAO 2010/11/01 APPR:MSASAO 2010/11/01	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE DESIGN UNITS <b>METRIC</b>		THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE			
	10 OVER 30 UNDER	±0.25	Y. WADA	2004/3/4	<b>0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)</b>			
	30 OVER	±0.3	CHECKED BY	DATE				
ANGULAR ±3 °		APPROVED BY M. SASAO 2004/3/4		MOLEX INCORPORATED		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. <b>SEE CHART</b>		DOCUMENT NO. <b>SD-53353-003</b>		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

53353-\*\*\*29 (位置決め用ボス無)  
(WITHOUT LOCATING BOSS)

嵌合相手 MATES WITH  
52465-\*\*\*19 (位置決め用ボス付)  
(WITH LOCATING BOSS)

52465-\*\*\*29 (位置決め用ボス無)  
(WITHOUT LOCATING BOSS)

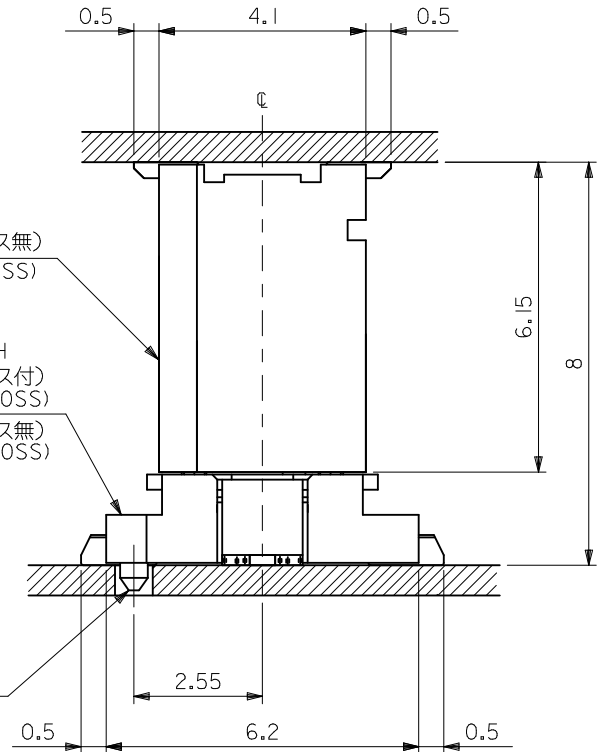


53353-\*\*\*29 (位置決め用ボス無)  
(WITHOUT LOCATING BOSS)

嵌合相手 MATES WITH  
52588-\*\*\*\* (位置決め用ボス付)  
(WITH LOCATING BOSS)

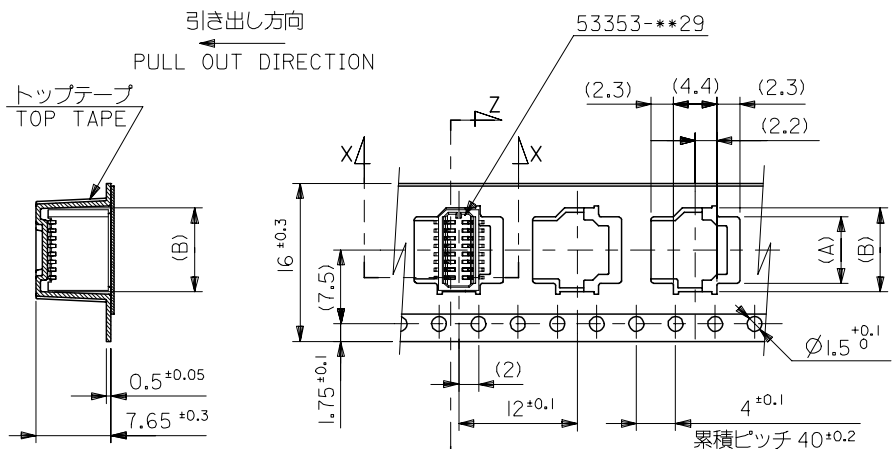
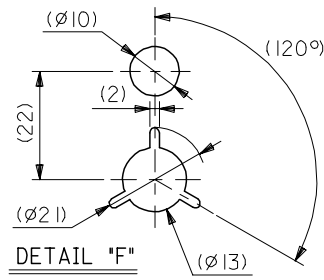
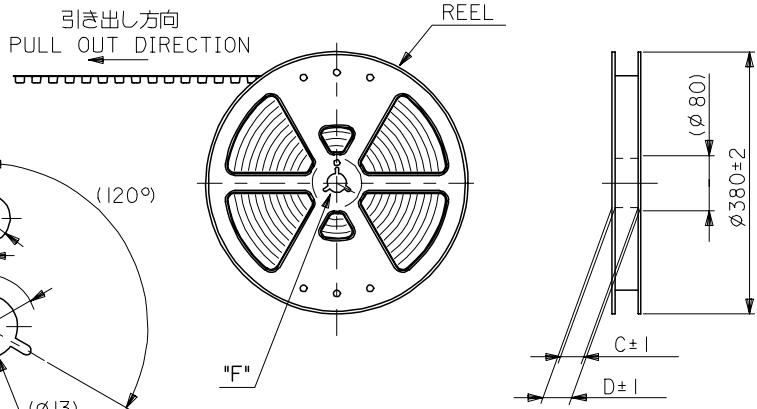
52588-\*\*\*\* (位置決め用ボス無)  
(WITHOUT LOCATING BOSS)

位置決め用ボス  
LOCATING BOSS

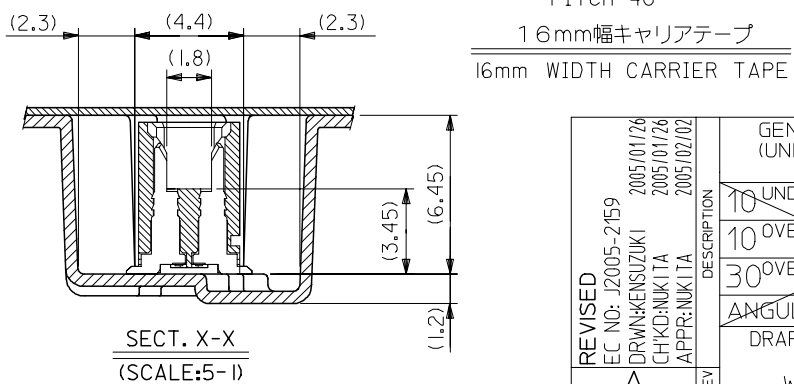


嵌合状態図 (参考)  
MATED DRAWING (REF.)

REVISED EC NO: J2011-0630 DRW:KTOYODA 2010/11/01 CHK:DMSASAO 2010/11/01 APPR:MSASAO 2010/11/01	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		CONNECTOR SERIES No. : 53353-***29				
		10 UNDER	± ---	DRAWN BY	DATE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		10 OVER 30 UNDER	± ---	Y. WADA	2004/3/4	+	METRIC	TITLE 0.8 B/B CONN. WAFER ASSY ST. SMT(WITHOUT BOSS)		
		30 OVER	± ---	M. SASAO	2004/3/4	MOLEX INCORPORATED			SHEET NO. 2 OF 2	
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY M. SASAO 2004/3/4		MATERIAL NO. SEE CHART			DOCUMENT NO. SD-53353-003	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SIZE A3						



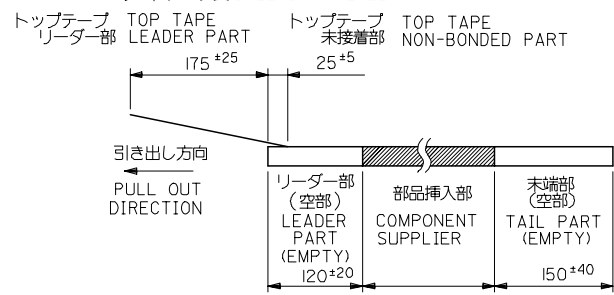
SECT. Z-Z



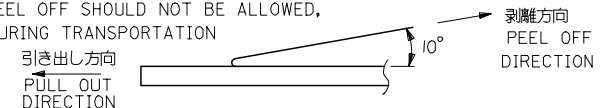
SECT. X-X  
(SCALE:5-1)

注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：(剥離方向は下図参照)  
0. 1~1. 3N {10~130gf} 尚、本規格値は、出荷時に適用。  
(但し、輸送時に剥離が発生しない事。)  
PEELING OFF FORCE OF TOP TAPE  
0. 1~1. 3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
PEEL OFF SHOULD NOT BE ALLOWED,  
DURING TRANSPORTATION

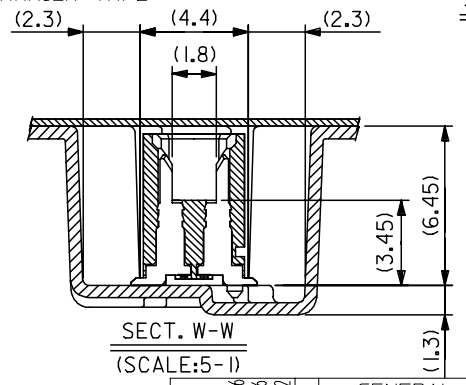
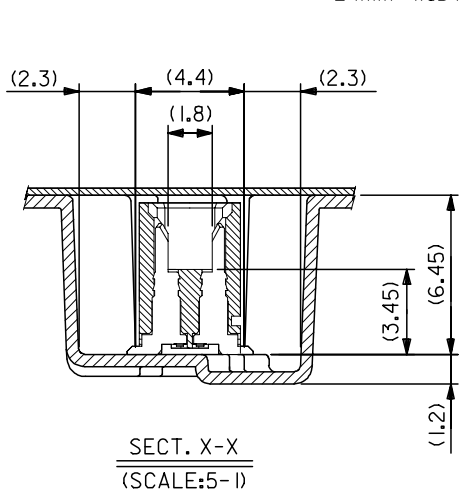
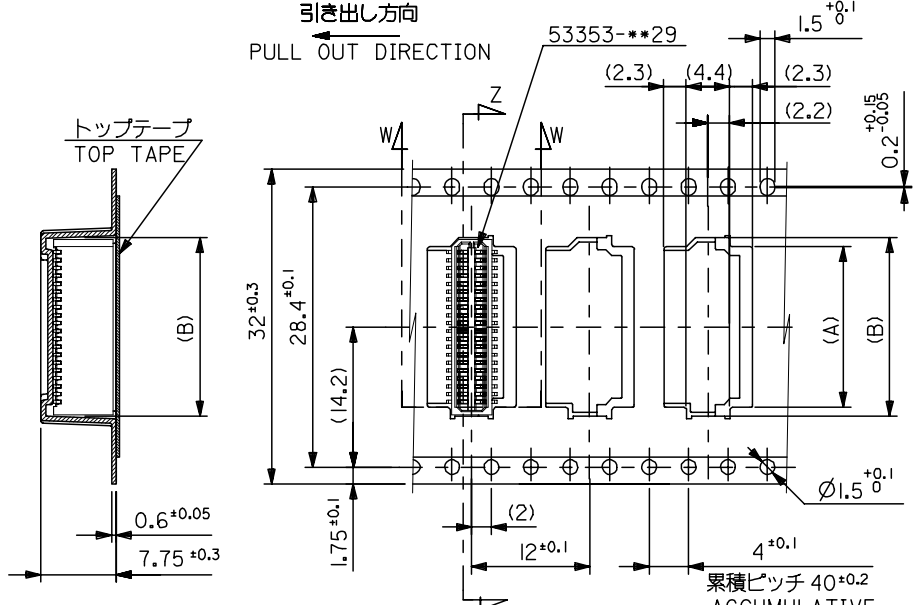
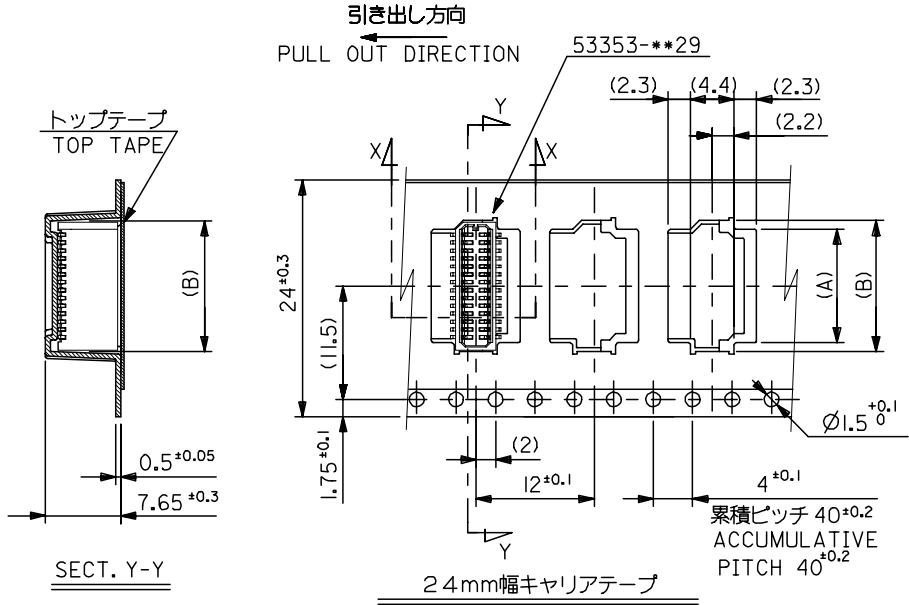


4. 材料 MATERIAL  
キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE  
トップテープ：PET, PE, PEF TOP TAPE:PET,PE,PEF  
リール：ポリスチレン (PS) REEL:POLYSTYRENE(PS)  
<リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>
5. 本製品は53353-\*\*-91の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53353-\*\*-91.

16	21.4	17.4	8.5	6.7	53353-1671	16
			7.7	5.9	53353-1471	14
			6.9	5.1	53353-1271	12
			6.1	4.3	53353-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

MODEL NO. 53353-\*\*-71

REVISED EC NO: J2005-2159 DRAWN: KENSUJUKI 2005/01/26 CHKD: NUKITA 2005/01/26 APPR: NUKITA 2005/02/02 REV A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MSASAO	DATE 2004/03/04	APPROVED BY MSASAO 2004/03/04		
	30 OVER	±0.3	APPROVED BY MSASAO 2004/03/04		MOLEX INCORPORATED		
	ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-53353-004	SHEET NO. 1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



キャリアテープ幅 CARRIER TAPE WIDTH		D		C		(B)	(A)	MATERIAL NO.	極数 CIRCUIT
32	37.4	33.4	18.1	16.3	53353-4071	40			
			16.5	14.7	53353-3671	36			
24	29.4	25.4	14.1	12.3	53353-3071	30			
			13.3	11.5	53353-2871	28			
			10.9	9.1	53353-2271	22			
			10.1	8.3	53353-2071	20			
			9.3	7.5	53353-1871	18			

REVISED EC NO: J2005-2159 DRAWN: KENSUJUKI CHKD: NUKITA APPR: NUKITA 2005/01/26 2005/01/26 2005/02/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY YWADA	DATE 2004/03/04	TITLE 0.8 BTB CONN WAFER ASSY ST SMT WITHOUT BOSS EMBTP PKG -LEAD FREE-			
	APPROVED BY MSASAO		DATE 2004/03/04		MOLEX INCORPORATED		DOCUMENT NO. SD-53353-004		SHEET NO. 2 OF 2
	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						